

General Description:

The LWS6028A4 uses advanced SGT technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. The package form is TO-252, which accords with the ROHS standard and Halogen Free standard.

Features:

- Fast Switching
- Low Gate Charge and $R_{DS(ON)}$
- Low Reverse transfer capacitances

Applications:

- Battery switching application
- Hard switched and high frequency circuits
- Power Management

100% DVDS Tested

100% Avalanche Tested



Package Marking and Ordering Information:

Marking	Part Number	Package	Packing	Qty.
S6028/LW A4/D.C.	LWS6028A4	TO-252	Reel	2500 Pcs

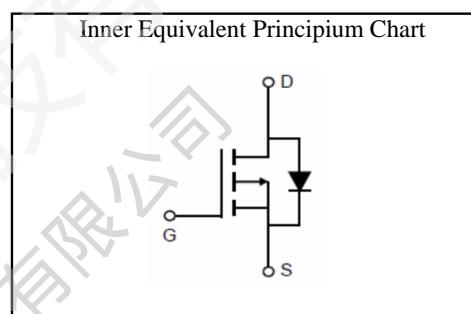
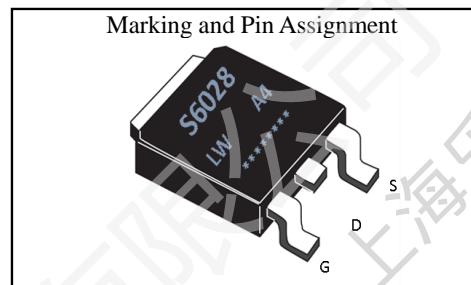
Absolute Maximum Ratings:

Symbol	Parameter		Value	Units
V_{DSS}	Drain-to-Source Voltage		-60	V
I_D	Continuous Drain Current	$T_C=25^\circ C$	-40	A
	Continuous Drain Current	$T_C=100^\circ C$	-25	A
I_{DM}^{a1}	Pulsed Drain Current		-150	A
V_{GS}	Gate-to-Source Voltage		± 20	V
P_D	Power Dissipation		95	W
E_{AS}^{a2}	Single pulse avalanche energy		200	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range		150, -55 to 150	°C
T_L	Maximum Temperature for Soldering		260	°C

Thermal Characteristics:

Symbol	Parameter		Value	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.32	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		60	°C/W

V_{DSS}	-60	V
I_D	-40	A
P_D	95	W
$R_{DS(ON)} \text{ TYPE}$	20	mΩ



Electrical Characteristic (T_A = 25 °C, unless otherwise specified):

Static Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
V _{DSS}	Drain to Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-60	--	--	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} =-60V, V _{GS} =0V	--	--	1.0	μA
I _{GSS(F)}	Gate to Source Forward Leakage	V _{GS} =-20V, V _{DS} =0V	--	--	100	nA
I _{GSS(R)}	Gate to Source Reverse Leakage	V _{GS} =+20V, V _{DS} =0V	--	--	-100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.3	-1.8	-2.3	V
R _{DSON1}	Drain-to-Source On-Resistance	V _{GS} =-10V, I _D =-10A	--	20	25	mΩ
R _{DSON2}	Drain-to-Source On-Resistance	V _{GS} =-4.5V, I _D =-8A	--	25	32	mΩ
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-5A	--	20	--	S

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
C _{iss}	Input Capacitance	V _{GS} = 0V V _{DS} = -30V f = 1.0MHz	--	1500	--	pF
C _{oss}	Output Capacitance		--	248	--	
C _{rss}	Reverse Transfer Capacitance		--	12	--	
R _G	Gate resistance	V _{GS} =0V, V _{DS} Open	--	8.0	--	Ω

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
t _{d(ON)}	Turn-on Delay Time	I _D = -10A V _{DS} = -30V V _{GS} = -10V R _G = 3Ω	--	15	--	ns
t _r	Rise Time		--	17	--	
t _{d(OFF)}	Turn-Off Delay Time		--	40	--	
t _f	Fall Time		--	45	--	
Q _g	Total Gate Charge	V _{GS} = -10V V _{DS} = -30V I _D = -10A	--	22	--	nC
Q _{gs}	Gate Source Charge		--	3.7	--	
Q _{gd}	Gate Drain Charge		--	3.0	--	

Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Value			Units
			Min.	Typ.	Max.	
I _S	Diode Forward Current	T _C = 25 °C	--	--	-40	A
I _{SM}	Diode Pluse Current		--	--	-150	A
V _{SD}	Diode Forward Voltage	I _S =-10A, V _{GS} =0V	--	--	-1.2	V
t _{rr}	Reverse Recovery time	I _S =-10A, V _{DD} =-30V, dI/dt=100A/us	--	60	--	ns
Q _{rr}	Reverse Recovery Charge		--	105	--	nC

a1: Repetitive rating; pulse width limited by maximum junction temperature

a2: V_{DD}=-30V, L=1.0mH, R_G=25Ω, Starting T_j=25°C

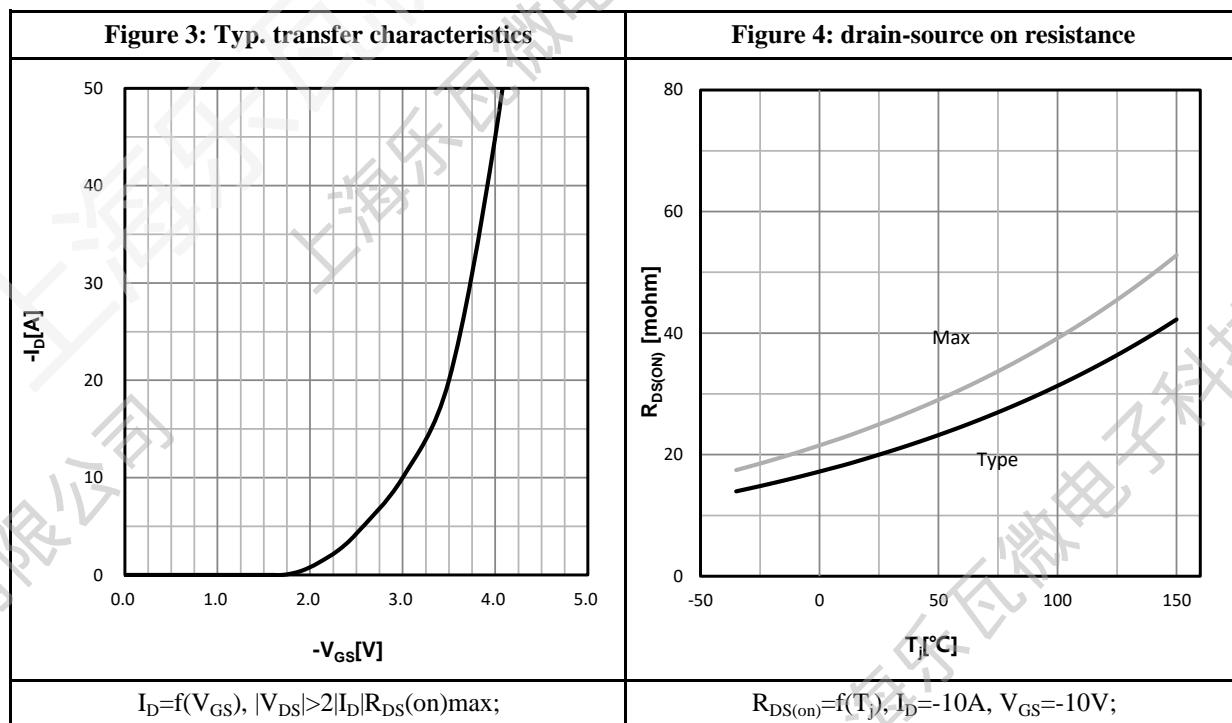
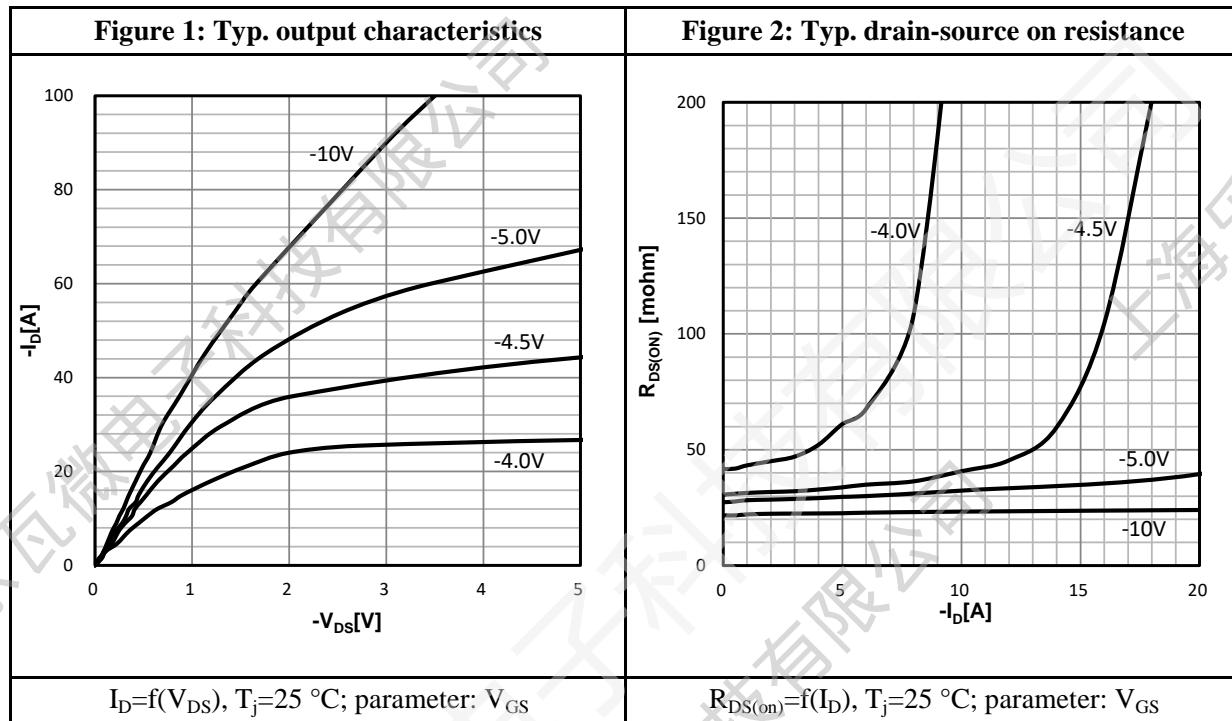
Characteristics Curve:


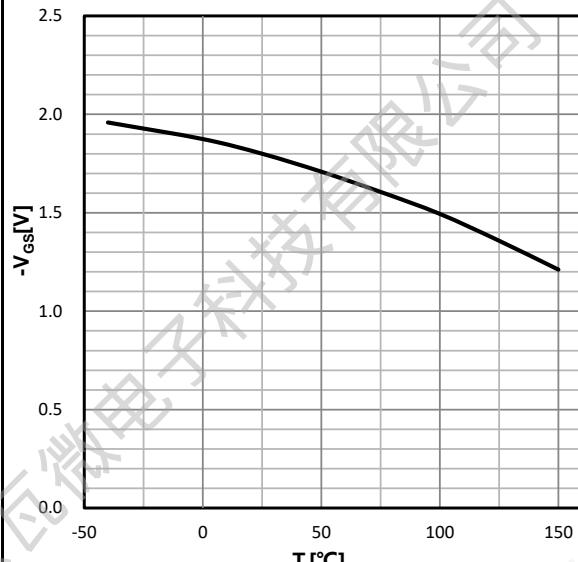
Figure 5: Typ. gate threshold voltage

 $V_{GS}=f(T_j)$, $V_{GS}=V_{DS}$, $I_D=-250\mu A$;

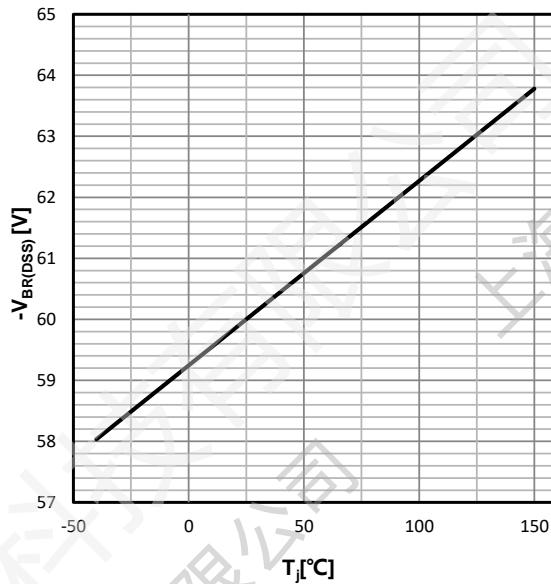
Figure 6: Drain-source breakdown voltage

 $V_{BR(DSS)}=f(T_j)$; $I_D=-250\mu A$;

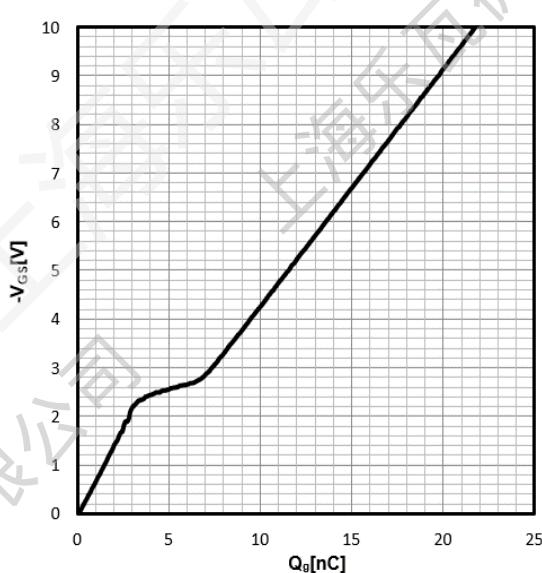
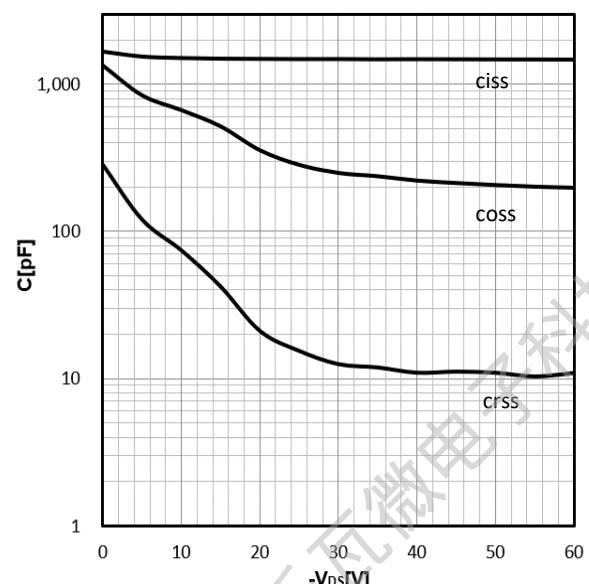
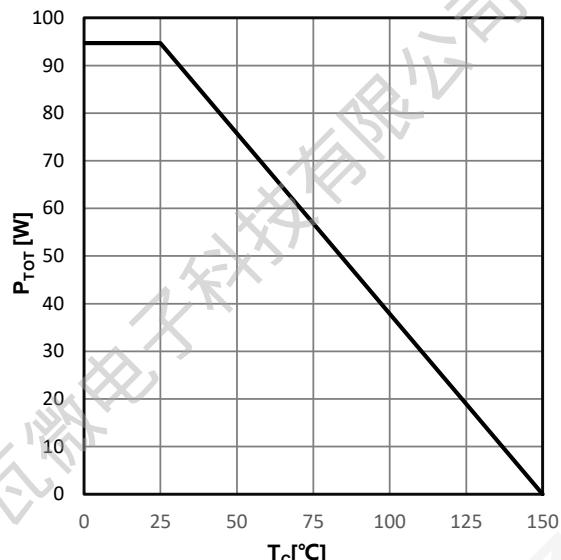
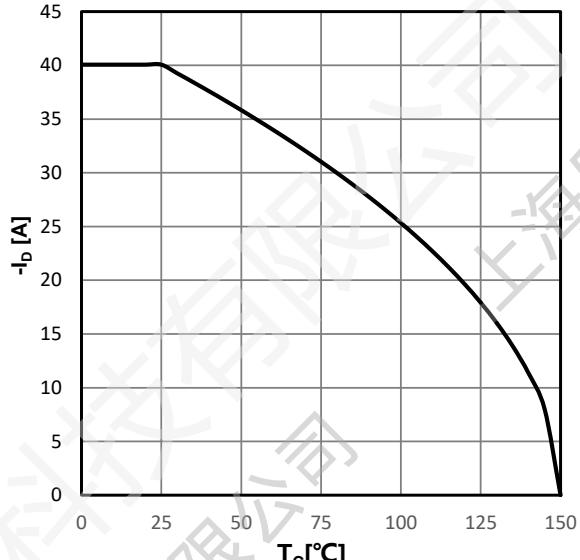
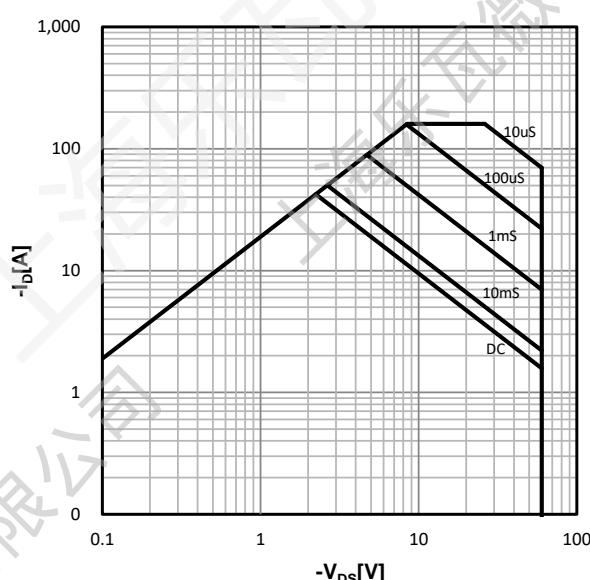
Figure 7: Typ. gate charge

 $V_{GS}=f(Q_g)$, $I_D=-10A$, $T_j=25$ °C; parameter: V_{DS}
Figure 8: Typ. Capacitances

 $C=f(V_{DS})$; $V_{GS}=0V$; $f=1.0$ MHz;

Figure 9: Power dissipation


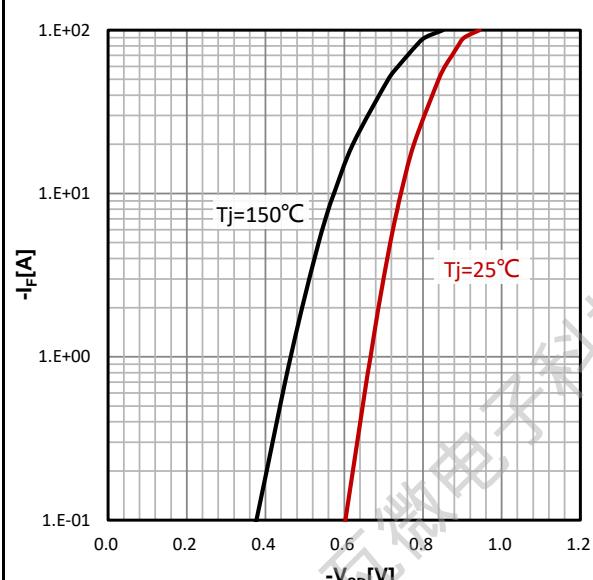
$$P_{\text{tot}} = f(T_c);$$

Figure 10: Drain current


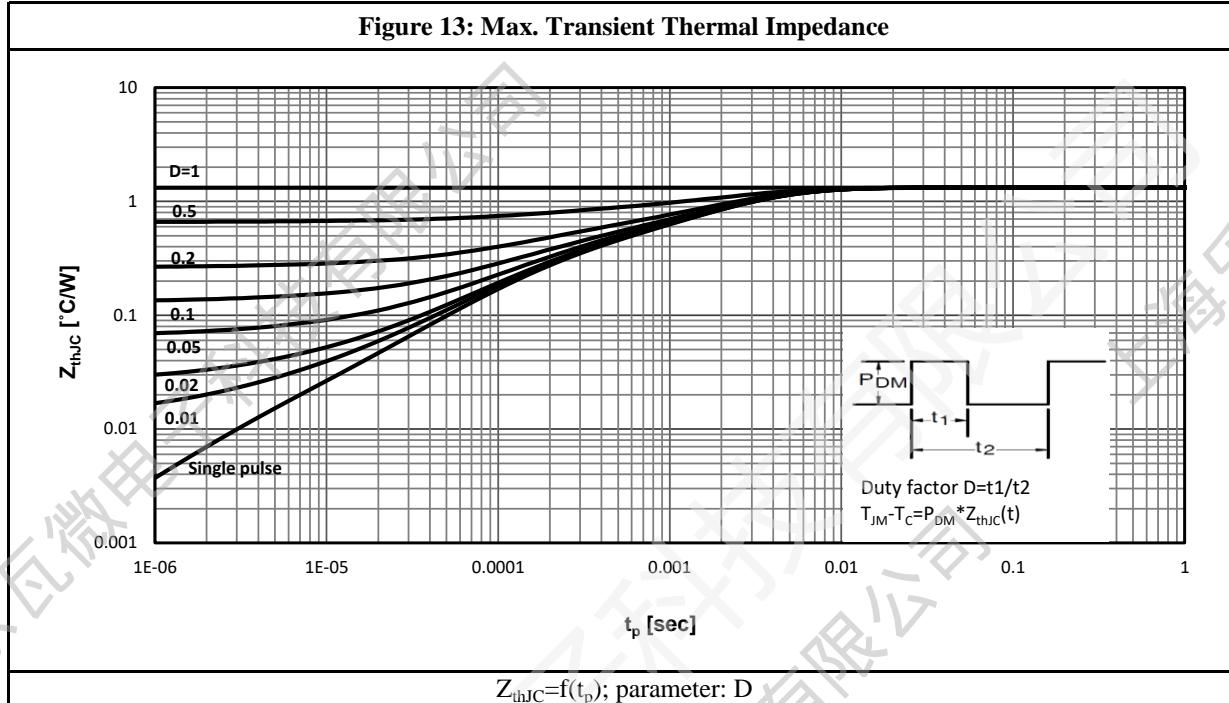
$$I_D = f(T_c);$$

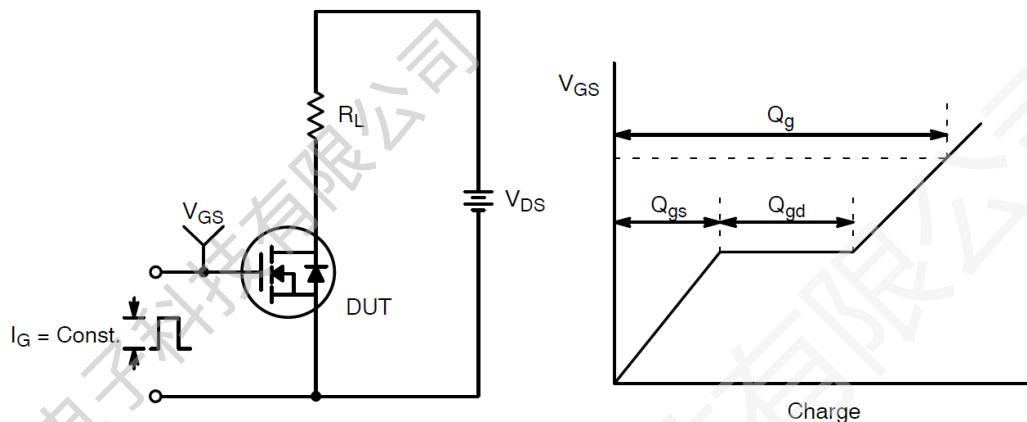
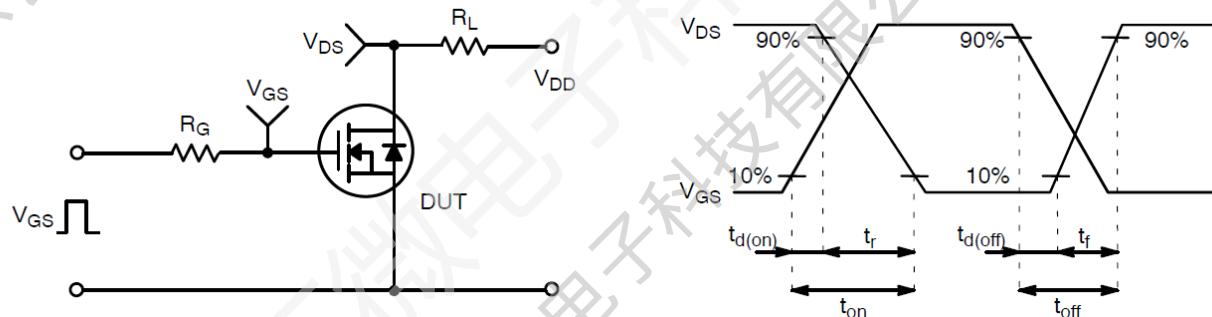
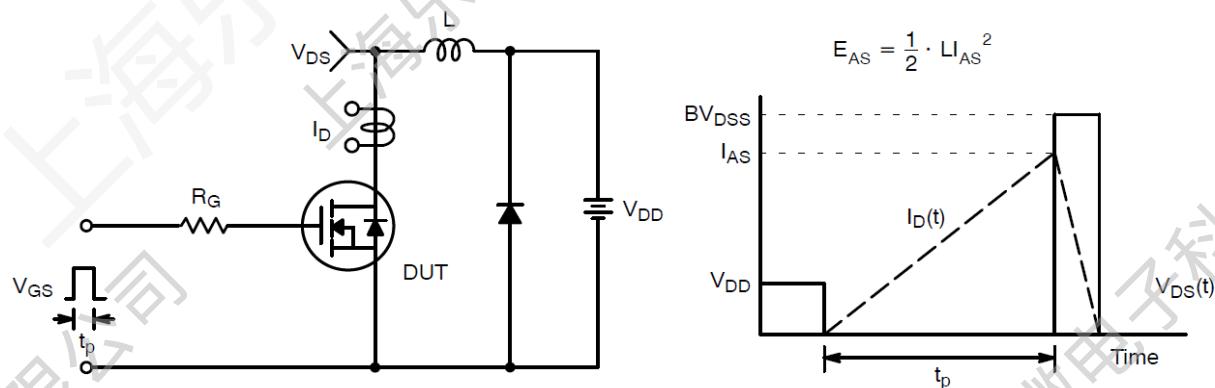
Figure 11: Safe operating area


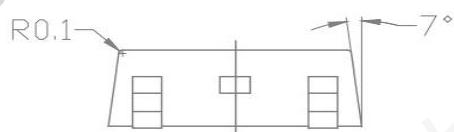
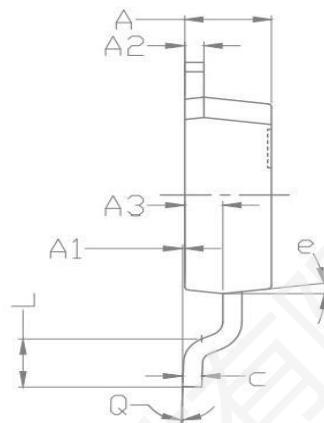
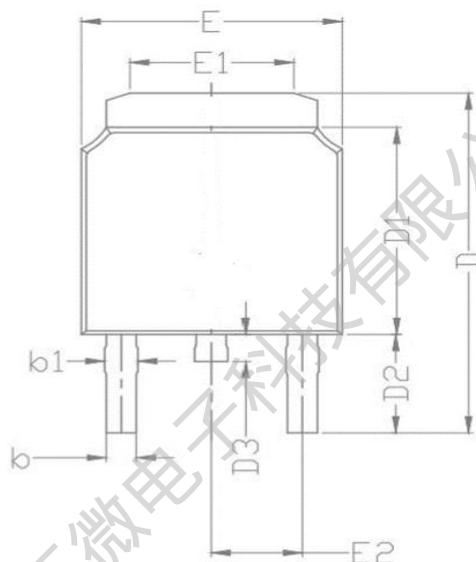
$$I_D = f(V_{DS}); T_c = 25^{\circ}\text{C}; D=0; \text{parameter: tp}$$

Figure 12: Typ. forward characteristics


$$I_F = f(V_{SD});$$

Figure 13: Max. Transient Thermal Impedance


Test Circuit & Waveform:

Figure 14: Gate Charge Test Circuit & Waveform

Figure 15: Resistive Switching Test Circuit & Waveforms

Figure 16: Unclamped Inductive Switching Test Circuit & Waveforms

Package Outline:


COMMON			
PKG	TO-252-2L		
Symbol	Min	Nom	Max
A	2.200	2.300	2.400
A1	0.000	0.075	0.150
A2	0.500	0.508	0.550
A3	0.960	1.010	1.060
b	0.740	0.760	0.800
b1	0.880	0.900	0.950
C	0.500	0.508	0.550
D	9.800	10.025	10.350
D1	6.050	6.100	6.180
D2	2.850	2.900	2.950
D3	0.600	0.800	1.000
E	6.550	6.600	6.700
E1	4.050	4.130	4.200
E2	2.25	2.286	2.3
L	1.400	1.500	1.600
e	7°		
Q	0°	2°	5°

Revision History:

Revison	Date	Descriptions
Rev 1.0	May.2022	Initial Version

Disclaimer:

The information in this document is believed to be accurate and reliable. However, no responsibility is assumed by LW-Micro for its use. All operating parameters must be designed, validated and tested to ensure they meet the requirements of your application. LW-Micro reserves the right to make any specification and/or circuitry changes without prior notification. Before starting a brand-new project, please contact LW-Micro Sales to get the most recent relevant information.

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